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(54) Title: DICING TAPE AND DIE ATTACH ADHESIVE WITH PATTERNED BACKING

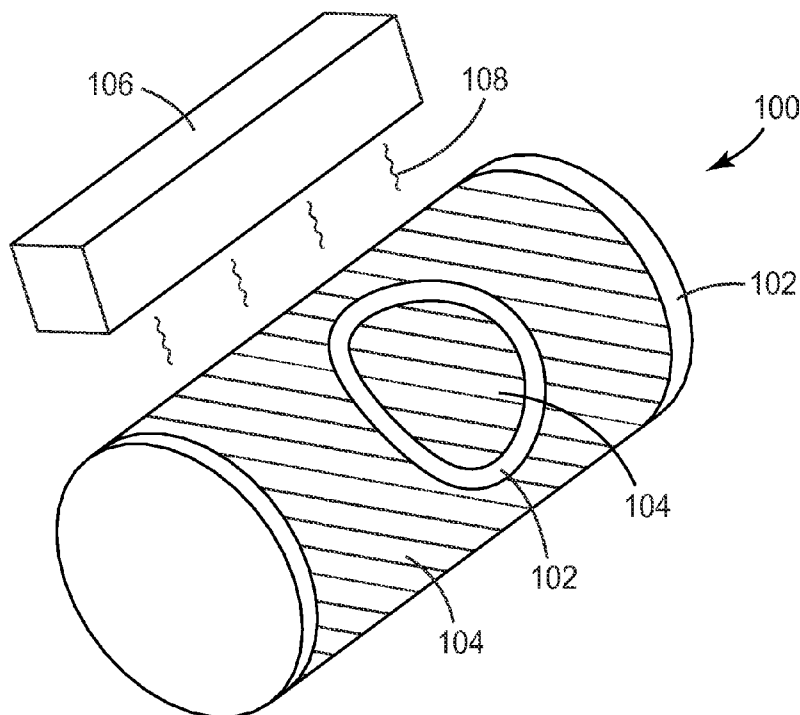


FIG. 1

(57) Abstract: Provided are a tape, apparatus, and method that relate generally to a single layer adhesive which functions as a dicing tape and also as a die attach adhesive for dicing thinned wafers and subsequent die attach operations of the diced chips in semiconductor device fabrication. The tape, apparatus, and method include a backing with a surface modification that includes a pattern.



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